



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20180710002
Qualification of JCET C8 as an Additional Assembly Site for
Select Devices in SOT-23 Package
Change Notification / Sample Request

Date: July 16, 2018
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20180710002
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS562201DDCR	null
TPS563201DDCR	null
SN1706011DDCR	null
TPS562201DDCT	null
SN1706011DDCT	null
TPS562208DDCR	null
TPS563208DDCR	null
TPS563208DDCT	null
TPS563201DDCT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180710002		PCN Date:	July 16, 2018													
Title:	Qualification of JCET C8 as an Alternate Assembly Site for Select Devices in SOT-23 Package																
Customer Contact:	PCN Manager		Dept:	Quality Services													
Proposed 1st Ship Date:	Oct 16, 2018		Estimated Sample Availability:	Provided upon Request													
Change Type:																	
☒	Assembly Site	☐	Design	☐	Wafer Bump Site												
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material												
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process												
☐	Mechanical Specification	☒	Test Site	☐	Wafer Fab Site												
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials												
		☐		☐	Wafer Fab Process												
PCN Details																	
Description of Change:																	
Texas Instruments is pleased to announce the qualification of JCET C8 as an alternate Assembly site for SOT-23 Package Devices. No material differences between sites:																	
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin</th> <th>Assembly Country Code</th> <th>Assembly City</th> </tr> </thead> <tbody> <tr> <td>JCET</td> <td>JCE</td> <td>CHN</td> <td>Jiangyin</td> </tr> <tr> <td>JCET C8</td> <td>JC8</td> <td>CHN</td> <td>Suqian</td> </tr> </tbody> </table>						Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly City	JCET	JCE	CHN	Jiangyin	JCET C8	JC8	CHN	Suqian
Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly City														
JCET	JCE	CHN	Jiangyin														
JCET C8	JC8	CHN	Suqian														
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.																	
Reason for Change:																	
Continuity of Supply																	
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):																	
None																	
Anticipated impact on Material Declaration																	
☒	No Impact to the Material Declaration	☐	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.														
Changes to product identification resulting from this PCN:																	
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin (22L)</th> <th>ASO:</th> </tr> </thead> <tbody> <tr> <td>JCET</td> <td></td> <td>JCE</td> </tr> <tr> <td>JCET C8</td> <td>Assembly Site Origin (22L)</td> <td>ASO: JC8</td> </tr> </tbody> </table>						Assembly Site	Assembly Site Origin (22L)	ASO:	JCET		JCE	JCET C8	Assembly Site Origin (22L)	ASO: JC8			
Assembly Site	Assembly Site Origin (22L)	ASO:															
JCET		JCE															
JCET C8	Assembly Site Origin (22L)	ASO: JC8															

Sample product shipping label (not actual product label)



Product Affected

PTPS563201DDCR	SN1708041DDCR	SN1711023DDCR	TPS563201DDCR
PTPS563201DDCT	SN1708041DDCT	SN1711023DDCT	TPS563201DDCT
SN1612030DDCR	SN1709020DDCR	TPS562201DDCR	TPS563208DDCR
SN1612030DDCT	SN1709020DDCT	TPS562201DDCT	TPS563208DDCT
SN1706011DDCR	SN1711021DDCR	TPS562208DDCR	
SN1706011DDCT	SN1711021DDCT	TPS562208DDCT	

Qualification Report

Augusta-Next Family JCET C8 Qualification
(RFAB, JCAP B2, JCET C8)

Date: 06/29/2018

Product Attributes

Attributes	Qual Device: <u>TPS563208DDC</u>	Qual Device: <u>TPS562201DDC</u>	QBS Product Reference: <u>TPS563208DDC</u>	QBS Product Reference: <u>TPS562201DDC</u>	QBS Product Reference: <u>TPS563201DDC</u>	QBS Process Reference: <u>TPS65265RHB</u>
Assembly Site	JCET C8	JCET C8	JCET C3	JCET C3	JCET C3	CLARK-AT
Package Family	SOT	SOT	SOT	SOT	SOT	QFN
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	RFAB	RFAB	RFAB	RFAB	RFAB	RFAB
Wafer Process	LBC7	LBC7	LBC7	LBC7	LBC7	LBC7

- QBS: Qual By Similarity

- Qual Device TPS563208DDC, TPS562201DDC are qualified at LEVEL1-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: <u>TPS563208DDC</u>	Qual Device: <u>TPS562201DDC</u>	QBS Product Reference: <u>TPS563208DDC</u>
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass
HBM	ESD - HBM	3000V	-	-	1/3/0
CDM	ESD - CDM	1500 V	-	-	1/3/0
LU	Latch-up	(per JESD78)	-	-	1/6/0
HTOL	Life Test, 125C	1000 Hours	-	-	-
HTSL	High Temp Storage Bake, 170C	420 Hours	3/231/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0	-	-

Type	Test Name / Condition	Duration	Qual Device: <u>TPS563208DDC</u>	Qual Device: <u>TPS562201DDC</u>	QBS Product Reference: <u>TPS563208DDC</u>
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0	1/77/0
PD	Physical Dimensions	(per mechanical drawing)	3/15/0	-	-
SD	Surface Mount Solderability	Dry Bake 155C (4hours +/-15minutes); Pb-Free Solder	3/66/0	-	-
SD	Surface Mount Solderability	Dry Bake 155C (4hours +/-15minutes); Pb Solder	3/66/0	-	-

Type	Test Name / Condition	Duration	QBS Product Reference: <u>TPS562201DDC</u>	QBS Product Reference: <u>TPS563201DDC</u>	QBS Process Reference: <u>TPS65265RHB</u>
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass
HBM	ESD - HBM	3000V	1/3/0	1/3/0	-
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	1/3/0
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	1/6/0
HTOL	Life Test, 125C	1000 Hours	-	1/77/0	3/231/0
HTSL	High Temp Storage Bake, 170C	420 Hours	-	3/231/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	3/231/0	-
PD	Physical Dimensions	(per mechanical drawing)	-	-	-
SD	Surface Mount Solderability	Dry Bake 155C (4hours +/-15minutes); Pb-Free Solder	-	-	-
SD	Surface Mount Solderability	Dry Bake 155C (4hours +/-15minutes); Pb Solder	-	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

THIS INFORMATION RELATING TO QUALITY AND RELIABILITY IS PROVIDED "AS IS." Product information detailed in this report may not accurately reflect TI's current product materials, processes and testing used in the construction of the TI products. Customers are solely responsible to conduct sufficient engineering and additional qualification testing to determine whether a device is suitable for use in their applications. Using TI products outside limits stated in TI's datasheet may void TI's warranty. See TI's Terms of Sale at "<http://www.ti.com/lscds/ti/legal/termsofsale.page>"

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com